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## GLOSSARY OF TECHNICAL TERMS

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*This glossary contains explanations of certain terms, definitions and abbreviations used in this prospectus in connection with our Group and our business. The terms and their meanings may not correspond to standard industry meaning or usage of those terms.*

“Advanced Product Quality Planning” or “APQP”	a framework of procedures and techniques used to develop new products in industrial production that starts with a concept and ends with product and process validation
“AEC-Q101”	a set of standards developed by Automotive Electronics Council (AEC) for the supply of discrete parts in the automotive electronics industry
“axial and through-hole packaging”	one of the methods to package DO series products
“bridge rectifier”	a type of full-wave rectifier which has four elements connected as a bridge circuit with direct voltage obtained from one pair of opposite junctions when alternating voltage is applied to the other pair
“clip bonding”	the process which connects die and lead by a solid copper bridge, which is also soldered by solder paste
“Darlington transistor”	a type of transistor which has a compound structure consisting of two bipolar transistors connected in a way that the current amplified by the first transistor is amplified further by the second one
“die” or “silicon die”	one individual chip cut from a wafer before being packaged
“die bonder”	a machine that picks die from wafer and mounts it onto a high density leadframe
“die bonding”	the process of connecting the package to the die (or chip) bonding pads
“digital transistor”	a type of transistor that combines resistors for convenience of digital circuit
“diode”	a semiconductor device with two terminals, typically allowing the flow of current in one direction only

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“discrete”, “discrete devices” or “discrete semiconductor”	a single silicon die, housed in a package, which performs a single function
“dispenser”	an automatic machine which is designed to release a specific amount of substance
“DFN”	dual flat no lead packages, which have leads on only two opposing package sides
“DO”	diode outline, a type of discrete semiconductor package, which could be either through-hole package or surface mount package
“DPAK”	discrete packaging, a type of TO series package mainly used for power discrete packaging
“ESD protection diode”	an electronic component used in electronic appliances, which is designed to provide protection from electrostatic discharge (ESD), the sudden flow of electricity between two electrically charged objects caused by contact, an electrical short, or dielectric breakdown
“epoxy moulding compound” or “EMC”	one of the major materials used in package assembly, which can be heated to a liquid and then injected over a circuit for protection
“FAB process”	one of the processes in semiconductor manufacturing, which forms hundreds to thousands of chips on the wafer
“fast recovery rectifier”	a type of rectifier which switches current quickly
“former”	a machine used in the semiconductor packaging and assembly process
“handler”	a machine used in the semiconductor packaging and assembly process
“high voltage switching diode”	a type of diode designed for high voltage and high speed switching applications

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“IECQ”	the International Electrotechnical Commission Quality Assessment System for Electronic Components, a worldwide approval and certification system covering the supply of electronic components and associated materials and assemblies (including modules) and processes
“IECQ QC080000”	the standard for hazardous substance process management, as approved by the International Electrotechnical Commission, to restrict the use of hazardous substances in electronic products
“ISO”	International Organization for Standardization
“ISO 9001”	a quality management system model published by ISO for quality assurance in design, development, production, installation and servicing
“ISO 14001”	a set of standards published by ISO, which specifies a framework of control for an environmental management system
“laser”	a narrow beam of concentrated light produced by a machine, such as a laser marker, to cut or engrave semiconductors in the manufacturing process
“laser marker”	a machine that engraves characters or logos on the surface of semiconductors
“leadframe”	one of the major materials used in semiconductor package assembly, which serves as a platform for assembling the dies and interconnections prior to encapsulation
“LBF”	a type of bridge rectifier package
“LED”	Light-emitting Diode, a two-lead semiconductor light source
“mounting”	a step to process the components in the semiconductor manufacturing. During this process, the wafer is mounted on a plastic tape. The adhesive film on which the wafer is mounted ensures that the individual dies remain firmly in place during the process of cutting the wafer into dies

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“MOSFET”	Metal Oxide Semiconductor Field Effect Transistor, a type of transistor used for amplifying or switching electronic signals
“moulding machine”	a machine used to process components in the semiconductor manufacturing
“NPN/PNP small digital transistor”	a type of transistor
“ODM”	Original Design Manufacturing, a business model where a product is designed and manufactured by one company as specified, and is eventually rebranded by another firm for sale
“OEM”	Original Equipment Manufacturing, a business model where a product is manufactured by one company, and then purchased by another firm, and eventually retailed under that purchasing company’s brand name
“OHSAS 18001”	Occupational Health and Safety Management System, an internationally applied standard for occupational health and safety management systems
“OSAT”	Outsourced Semiconductor Assembly and Test
“passivated chip”	a type of silicon die
“photolithographic”	a process used in micro-fabrication to pattern parts of a thin film or the bulk of a substrate
“plating”	forming a layer of metal on an object from a plating solution
“PPAP”	Production Part Approval Process, the industry standard of production part approval process, which is developed to ensure engineering design record and specification requirements are consistently met
“PC”	personal computer
“PV”	photovoltaic, a method of converting solar energy into direct current
“Power-SO”	a type of small outline package

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“power transistor”	a type of transistor designed for high power
“QFN”	quad flat no lead packages, a type of discrete semiconductor package with single or multi-die
“REACH”	Regulation on Registration, Evaluation, Authorisation and Restriction of Chemicals, an European Union regulation on the production and use of chemical substances, as well as their potential impacts on both human health and the environment
“rectifier”	a type of semiconductor device, which converts an alternating current into a direct one by allowing a current to flow through it in one direction only
“reference design”	a technical blueprint of a system that is intended for others to copy
“regulator”	a type of semiconductor
“RoHS”	Restriction of Hazardous Substances Directive, an European Union directive that restricts the use of six hazardous materials in the manufacture of various types of electronic and electrical equipment
“SC-70”	a type of semiconductor package
“schottky barrier diodes”	an electronics component widely used for radio frequency in semiconductors
“schottky barrier rectifier”	a type of rectifier
“semiconductor”	a solid material whose electrical conductivity at room temperature is between that of a conductor and that of an insulator
“server”	a running instance of application software capable of accepting requests from the client and giving responses accordingly
“small signal transistor” or “SST”	a type of transistor

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“solder paste”	a substance used to connect the leads of surface mount integrated chip packages to attachment points (lands) in the circuit patterns on a printed circuit board
“solution kits”	a prototype with a list of electronic components put together to form a specific application
“SOD”	small outline diode, a type of small size, lead, and surface mount discrete semiconductor packages
“SOT”	small outline transistor, a type of surface mount discrete semiconductor packages
“sq.m”	square metre(s)
“storage”	an electronic memory device for storing data
“substrate”	a solid substance onto which a semiconductor device and other electronic parts can be applied
“surface mount”	a method for constructing electronic circuits in which the components are mounted directly onto the surface of printed circuit boards
“surge current”	a short-duration, high-amperage electric current wave, generally caused by a voltage imbalance, that may sweep through an electrical network
“switching diode”	a type of diode, with low resistance and with the normal forward voltage/current characteristic
“tablet”	a mobile computer with touch-screen display
“transient voltage suppressor”	an array of electronic devices that are designed to react to sudden or momentary overvoltage conditions
“thyristor”	a four-layered semiconductor rectifier in which the flow of current between two electrodes is triggered by a signal at a third electrode
“TO”	transistor outline, a type of discrete semiconductor package
“transistor”	a semiconductor device used to amplify and switch electronic signals and electrical power

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“trimmer”	a machine used to process components in the semiconductor manufacturing which cut and neaten the encapsulates
“trimming”	a step to process the components using a trimmer
“triode”	a semiconductor rectifier with three connections
“wafer”	a thin slice of semiconductor material, such as a silicon crystal, on which arrays of integrated circuits or discrete devices are fabricated during the manufacturing process
“wafer level chip scale packaging” or “WLCSP”	one of the methods to package discrete semiconductors
“wire bonder”	a machine used to bind the wire to the die
“wire bonding”	the process of connecting a fine wire between an on-chip pad and a substrate pad
“zener diodes”	a type of semiconductor diode in which a large reverse current can flow at a critical reverse voltage